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WHAT IS CLAIMED IS:

1. Method for transporting and inspecting semiconductor substrates, comprising the steps of:
 - providing at least three workstations arranged in a housing, wherein a changer being arranged in such a way that each of the workstations can be supplied with a semiconductor substrate ;
 - lifting the changer and carrying out a rotational movement by a specific angular amount, in order to transfer at least one of the semiconductor substrates to another workstation;
 - lowering the changer and carrying out a rotational movement by the same angular amount in the opposite direction, without a semiconductor substrate resting on the changer; and
 - picking up a new semiconductor substrate from a substrate feed module.
2. Method according to Claim 1, wherein the angular amount is 120°.
3. Method according to Claim 1, wherein the first workstation defines a transfer position, at which the semiconductor substrates are transferred from a substrate feed module into the housing or are transported back from the housing into the substrate feed module.
4. Method according to Claim 1, wherein the second workstation defines a macro inspection, with which the deviation of the current position of the semiconductor substrate is determined and made available to the housing for the further inspection process of the semiconductor substrate, any change in position of the semiconductor substrate at the second workstation is prevented.
5. Method according to Claim 4, wherein an identification on the semiconductor substrate is determined at the second workstation.

6. Method according to Claim 4, wherein the orientation of the semiconductor substrate is determined at the second workstation by a notch on the semiconductor substrate being determined.
7. Method according to claim 4, wherein in the event of a visual macro inspection by the user, the changer is previously lowered and then rotated through -60° , in order to provide sufficient clearance at the second workstation, and in that after the visual macro inspection has been completed, the changer is again rotated through a further -60° .
8. Method according to Claim 1, wherein the third workstation defines a micro inspection with which defined locations on the semiconductor substrate are examined for faults with a microscope.
9. Arrangement for transporting and inspecting semiconductor substrates comprising: at least three workstations, a changer defining an axis of rotation, wherein the changer has at least three arms, and which is designed to load the at least three workstations with semiconductor substrates, the workstations being arranged coaxially around the axis of rotation of the changer, a measuring device is assigned to one workstation, wherein the measuring device determines the deviation of the current position of the semiconductor substrate from an intended position and makes it available to the arrangement for the further inspection of the semiconductor substrate and in that the changer is not equipped with means for moving the semiconductor substrates into the intended position.
10. Arrangement according to Claim 9, wherein the arms of the changer are mounted at an angle of 120° from one another.
11. Arrangement according to Claim 9, wherein three workstations are

provided and a first workstation defines a transfer position, at which semiconductor substrates are introduced into the arrangement from a substrate feed module and can be transferred from the arrangement to the substrate feed module.

12. Arrangement according to Claim 11, wherein a second workstation defines a macro inspection, with which the deviation of the current position of the semiconductor substrate is determined by the measuring device.

13. Arrangement according to Claim 12, wherein the macro inspection permits visual macro inspection of the front and rear sides of the semiconductor substrate and which pivots and rotates the semiconductor substrate in the field of view of a user.

14. Arrangement according to Claim 11, wherein the a workstation defines a micro inspection and comprises an x/y table, which feeds the semiconductor substrate to a microscope and permits displacement in the z direction.

15. Arrangement according to Claim 14, wherein the x/y table has a cut-out, which provides the lowered changer with the clearance for free rotation.

16. Arrangement according to Claim 9, characterized in that the arrangement is surrounded by a housing which provides the clean-room conditions intended for the entire arrangement.

17. Arrangement for transporting and inspecting semiconductor substrates comprising:

- a first, second and third workstation,

- a changer defining an axis of rotation, wherein the changer has three arms, and which is designed to load and unload the three workstations with semiconductor substrates,
- the first workstation defines a transfer position, at which semiconductor substrates are introduced into the arrangement from a substrate feed module and can be transferred from the arrangement to the substrate feed module,
- the second workstation is a measuring device, which determines the deviation of the current position of the semiconductor substrate from an intended position and makes it available to the arrangement for the further inspection of the semiconductor substrate, and
- the third workstation defines a micro inspection and comprises an x/y table, which feeds the semiconductor substrate to a microscope.

18. The arrangement according to claim 17 wherein the changer is not equipped with means for moving the semiconductor substrates into the intended position at the measuring device.

19. The arrangement according to claim 17 wherein the x/y table has a cutout, which provides the lowered changer with the clearance for free rotation.